DRA2523E

Silicon PNP epitaxial planar type

For digital circuits

Complementary to DRC2523E

Features

- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

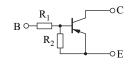
Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	-50	V	
Collector-emitter voltage (Base open)	V _{CEO}	-50	V	
Collector current	I _C	-500	mA	
Total power dissipation	P _T	200	mW	
Junction temperature	Tj	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

- Package
- Code
- Mini3-G3-B
- Pin Name
 - 1: Base
 - 2: Emitter
 - 3: Collector

Marking Symbol: SH

Internal Connection



Resistance	R ₁	2.2	kΩ
value	R ₂	2.2	kΩ

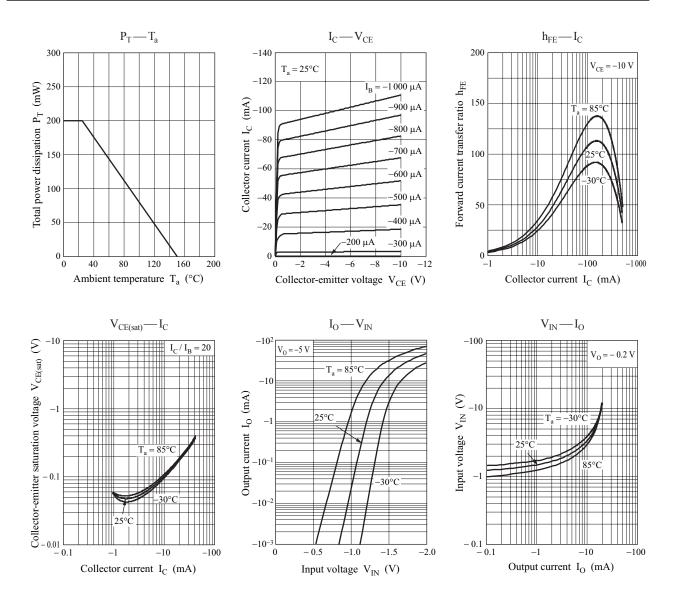
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = -10 \ \mu {\rm A}, I_{\rm E} = 0$	-50			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -2 {\rm mA}, I_{\rm B} = 0$	-50			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = -50 \text{ V}, I_E = 0$			-1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{\rm CE} = -50$ V, $I_{\rm B} = 0$			-1	μA
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{\rm EB} = -6 \text{V}, \text{I}_{\rm C} = 0$			-5	mA
Forward current transfer ratio	$h_{\rm FE}$	$V_{CE} = -10 \text{ V}, I_C = -100 \text{ mA}$	40			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -100 \text{ mA}, I_{\rm B} = -5 \text{ mA}$			-0.25	V
Input voltage (ON)	V _{I(on)}	$V_{CE} = -0.2 \text{ V}, I_C = -50 \text{ mA}$	-2.6			V
Input voltage (OFF)	V _{I(off)}	$V_{CE} = -5 V, I_C = -100 \mu A$			-0.7	V
Input resistance	R ₁		-30%	2.2	+30%	kΩ
Resistance ratio	R_1 / R_2		0.8	1.0	1.2	

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

DRA2523E

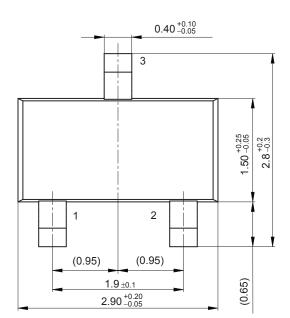
Panasonic

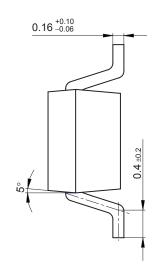


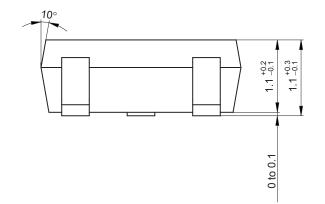
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Mini3-G3-B

Unit: mm







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